

**2018 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2018)  
& 2018 IEEE International Conference on Smart Manufacturing, Industrial & Logistics  
Engineering (IEEE SMILE 2018)**

**Conference Chairs: Chen-Fu Chien, Jei-Zheng Wu, & Runliang Dou**

**February 7 - 9, 2018, Hsinchu, Taiwan**

**Aims and Topics:**

The joint conference of 2018 International Symposium on Semiconductor Manufacturing Intelligence (ISMI2018) and 2018 IEEE International Conference on Smart Manufacturing, Industrial & Logistics Engineering (SMILE 2018) aims to disseminate recent theoretical and methodological developments, applications, and case studies in light of ongoing revolutions for manufacturing intelligence and smart manufacturing. **Topics of interest include, but are not limited to, the following:**

Big Data Analytics & Data Mining for Smart Manufacturing	Industry 4.0 & Cyber-Physical Systems
AI & Computational Intelligence for Smart Manufacturing	Advanced Process Control/ Advanced Equipment Control
Internet of Things (IOT)	Virtual Metrology, Tool Health, Fault Detection & Classification
Manufacturing Intelligence, Evolutionary Algorithms	Circular Economics, Green Supply Chain & Sustainability
Decision Technologies, Modeling & Decision Analysis	Augmented Reality, Virtual Reality
Simulation Optimization & Applications	Manufacturing Strategy & Manufacturing Innovation
Corporate Resource Planning & ERP	User Experience & Innovative Design
Smart Production Facilities & Green Fab	Human-machine Collaboration, Ergonomics & Safety
Predictive Maintenance, Quality & Reliability	Total Resource Management & Overall Resource Effectiveness
Semiconductor & High-tech Manufacturing	Applications of Industrial Engineering & Logistics

**Organized/sponsored by:**

NTHU-TSMC Center for Manufacturing Excellence, National Tsing Hua University  
Industrial Engineering and Management Program, Ministry of Science and Technology, Taiwan  
Society for Excelling Enterprises and Decisions (SEED), Taiwan

**Paper submission:**

All papers must be written in English with a maximum length of 6 pages. Paper format, submission, and related information is updated: <https://ismi2018.decisions.org.tw/> and submission page: <https://www.easychair.org/conferences/?conf=ismi2018>. For more details, please consult Conference General Co-Chair, Professor Jei-Zheng Wu ([jzwu@scu.edu.tw](mailto:jzwu@scu.edu.tw)).

**Special Issues for Post-Conference Publication:**

Conference proceedings of full papers will be published by IEEE Xplore that is indexed by Ei Compendex. Selected papers will be recommended for reviews and possible publications in special issues of SCI journals including *Journal of Intelligent Manufacturing*, *Computers & Industrial Engineering*, and others.

**Important Dates:**

Deadline for Full Paper Submission for EI-Indexed Proceedings for IEEE Xplore:	<b>October 31, 2017 (==CLOSE==)</b>
Deadline for Presentation-only Abstract Submission:	<b>December 31, 2017</b>
Deadline for Full Paper Submission (for Best Paper/Student Paper Award entry):	<b>December 31, 2017</b>
Early Bird Registration (OPENED!!):	<b>December 31, 2017</b>
Camera Ready Manuscript Submission:	<b>January 14, 2018</b>

**Registration Fee:**

Full registration:	<b>US\$500</b> (Early bird, before December 10, 2017) / <b>US\$600</b> (Regular)
Student registration:	<b>US\$350</b> (Early bird, before December 30, 2017) / <b>US\$400</b> (Regular)

**Tutorial Session, Exhibit, and Factory Visiting:**

This conference will provide a platform for related activities such as tutorial, exhibit, and factory visiting to enrich conference.

**Venue: National Tsing Hua University** (<http://nthu-en.web.nthu.edu.tw/bin/home.php>) (special offers of NTHU guest house and hotels nearby are available; visitor guide will be provided in advance for visiting Taiwan and local tours).

**iSMI**



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